

P-Channel Enhancement Mode Power MOSFET

DESCRIPTION

The HM70P03K uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V.

GENERAL FEATURES

• $V_{DS} = -30V, I_{D} = -70A$

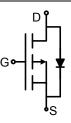
 $R_{DS(ON)} < 12.5 m\Omega @ V_{GS} = -4.5 V$

 $R_{DS(ON)}$ < 8m Ω @ V_{GS} =-10V

- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

- Battery Switch
- Load switch
- Power management



Schematic diagram



Marking and pin assignment



TO-252-2L top view

Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM70P03K	HM70P03K	TO-252-2L	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	-70	Α
Drain Current-Pulsed (Note 1)	I _{DM}	-210	Α
Maximum Power Dissipation	P _D	130	W
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V

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Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} =-30 V , V_{GS} =0 V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_D=-250\mu A$	-1	-1.5	-3	V
D : 0	R _{DS(ON)}	V _{GS} =-10V, I _D =-30A	-	6.0	7.5	mΩ
Drain-Source On-State Resistance		V _{GS} =-4.5V, I _D =-30A	-	9	12.5	mΩ
Forward Transconductance	g FS	V _{DS} =-15V,I _D =-30A	10	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ 45\/\\ 0\/	-	1600	-	PF
Output Capacitance	C _{oss}	V_{DS} =-15V, V_{GS} =0V, F=1.0MHz	-	350	-	PF
Reverse Transfer Capacitance	C _{rss}	Γ-1.UIVIΠZ	-	300	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	10	-	nS
Turn-on Rise Time	t _r	V _{DD} =-15V, ID=-1A,	-	15	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10V, R_{GEN} =6 Ω	-	110	-	nS
Turn-Off Fall Time	t _f			70	-	nS
Total Gate Charge	Qg	\/ - 45\/ - 204	-	30	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =-15V,I _D =-30A V _{GS} =-10V	-	5.5	-	nC
Gate-Drain Charge	Q_{gd}	v _{GS} =-10v	-	8	-	nC
Drain-Source Diode Characteristics	•					
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-2.1A	-	-	-1.2	V
	•			•		

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

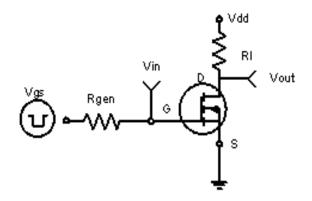


Figure 1:Switching Test Circuit

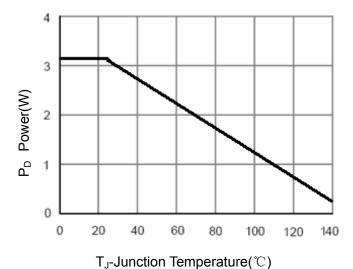


Figure 3 Power Dissipation

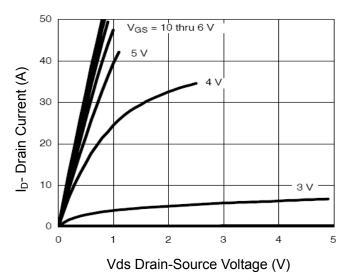


Figure 5 Output CHARACTERISTICS

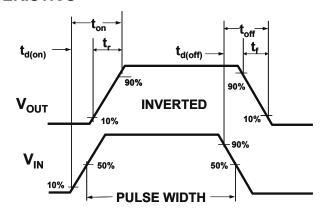


Figure 2:Switching Waveforms

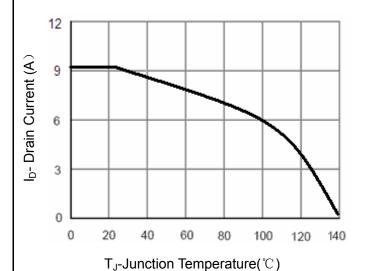


Figure 4 Drain Current

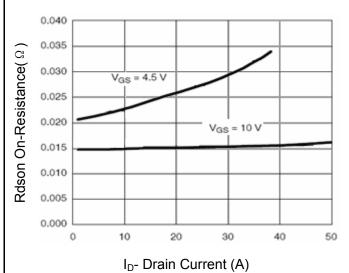


Figure 6 Drain-Source On-Resistance

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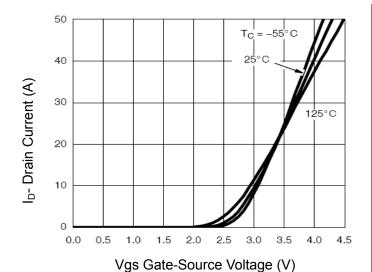
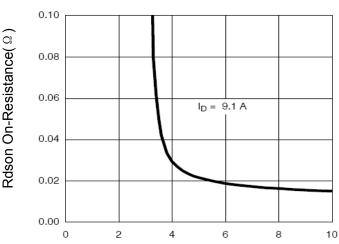


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)

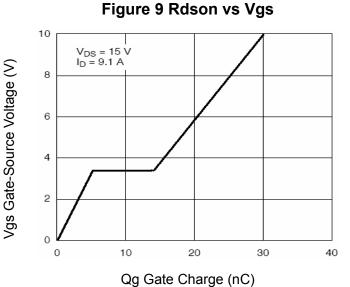


Figure 11 Gate Charge

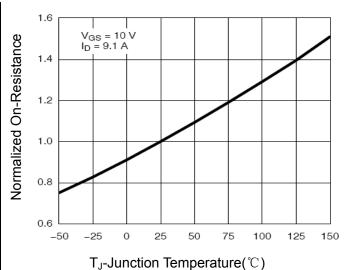


Figure 8 Drain-Source On-Resistance

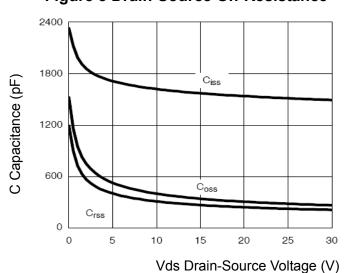


Figure 10 Capacitance vs Vds

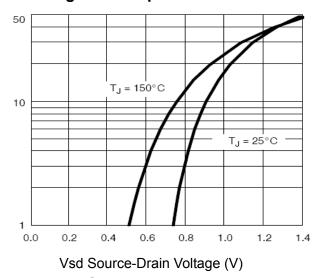
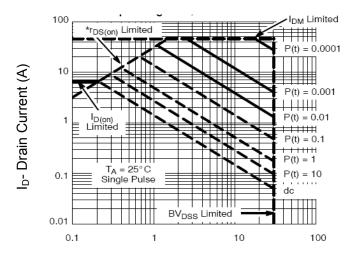


Figure 12 Source- Drain Diode Forward

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Is- Reverse Drain Current (A)

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Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

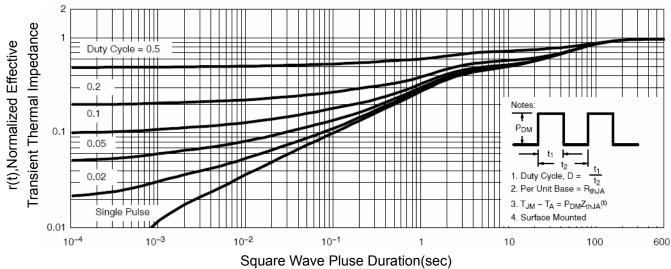
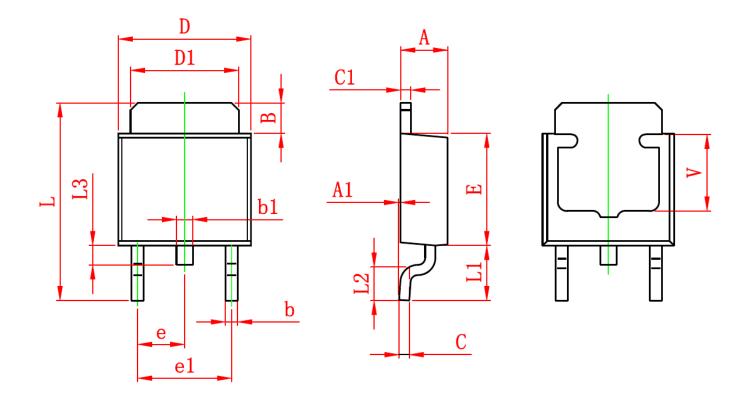


Figure 14 Normalized Maximum Transient Thermal Impedance

TO-252-2L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
E	5.400	5.700	0.213	0.224	
е	2.300	TYP.	0.091	TYP.	
e1	4.500	4.700	0.177	0.185	
L	9.500	9.900	0.374	0.390	
L1	2.550	2.900	0.100	0.114	
L2	1.400	1.780	0.055	0.070	
L3	0.600	0.900	0.024	0.035	
V	3.800	REF.	0.150 REF.		



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